



Material Content Data Sheet



Sales Product Name		BSF134N10NJ3 G		Issued		20. July 2018			
MA#		MA000845556							
Package		MG-WDSO-N-2-2		Weight*		50.20 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.788	5.55	5.55	55539	55539	
leadframe	non noble metal	copper	7440-50-8	44.951	89.55	89.55	895458	895458	
leadfinish	non noble metal	nickel	7440-02-0	0.143	0.28		2841		
	noble metal	silver	7440-22-4	0.567	1.13	1.41	11301	14142	
plating	non noble metal	nickel	7440-02-0	0.111	0.22	0.22	2202	2202	
glue	plastics	epoxy resin	-	0.141	0.28		2812		
	noble metal	silver	7440-22-4	0.867	1.73	2.01	17272	20084	
solder	non noble metal	copper	7440-50-8	0.003	0.01		52		
	noble metal	silver	7440-22-4	0.016	0.03		312		
	non noble metal	tin	7440-31-5	0.503	1.00	1.04	10021	10385	
passivation	plastics	epoxy resin	-	0.110	0.22	0.22	2190	2190	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com